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RENESAS TECHNICAL UPDATE

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Product Category	MPU/MCU		Document No.	TN-RL*-A0106A/E	Rev.	1.00
Title	Correction for Incorrect Description Notice RL78/I1D Descriptions in the User's Manual: Hardware Rev. 2.30 Changed		Information Category	Technical Notification		
Applicable Product	RL78/I1D Group	Lot No. All lots	Reference Document	RL78/I1D User's Manual: Hardware Rev. 2.30 R01UH0474EJ0230 (Jun. 2020)		

This document describes misstatements found in the RL78/I1D User's Manual: Hardware Rev. 2.30 (R01UH0474EJ0230).

Corrections

Applicable Item	Applicable Page	Contents
8.3.5 Real-time clock control register 1 (RTCC1)	Page 297	Incorrect descriptions revised
Figure 8 - 22 Procedure for Reading Real-time Clock 2	Page 312	Incorrect descriptions revised
Figure 8 - 23 Procedure for Writing Real-time Clock 2	Page 313	Incorrect descriptions revised
34.3.2 Supply current characteristics	Page 866 to Page 870	Incorrect descriptions revised

Document Improvement

The above corrections will be made for the next revision of the User's Manual: Hardware.

Corrections in the User's Manual: Hardware

No.	Corrections and Applicable Items			Pages in this document for corrections
	Document No.	English	R01UH0474EJ0230	
1	8.3.5 Real-time clock control register 1 (RTCC1)		Page 297	Page 3
2	Figure 8 - 22 Procedure for Reading Real-time Clock 2		Page 312	Page 4
3	Figure 8 - 23 Procedure for Writing Real-time Clock 2		Page 313	Page 4
4	34.3.2 Supply current characteristics		Page 866 to Page 870	Page 5 to Page 8

Incorrect: Bold with underline; Correct: Gray hatched

Revision History

RL78/I1D Correction for incorrect description notice

Document Number	Issue Date	Description
TN-RL*-A0106A/E	Jan. 19, 2023	First edition issued Corrections No.1 to No.4 revised (this document)

1. 8.3.5 Real-time clock control register 1 (RTCC1) (Page 297)

Incorrect:

Figure 8 - 8 Format of Real-time clock control register 1 (RTCC1) (3/3)

Address: FFF9EH After reset: 00H R/W

Symbol	<7>	<6>	<5>	<4>	<3>	2	<1>	<0>
RTCC1	WALE	WALIE	RITE	WAFG	RIFG	0	RWST	RWAIT

RWST	Wait status flag of real-time clock 2
0	Counter is operating.
1	Mode to read or write counter value.
This status flag indicates whether the setting of the RWAIT bit is valid. Before reading or writing the counter value, confirm that the value of this flag is 1. Even if the RWAIT bit is set to 0, the RWST bit is not set to 0 while writing to the counter. After writing is completed, the RWST bit is set to 0.	

RWAIT	Wait control of real-time clock 2
0	Sets counter operation.
1	Stops SEC to YEAR counters. Mode to read or write counter value.
This bit controls the operation of the counter. Be sure to write 1 to it to read or write the counter value. As the counter (16-bit) is continuing to run, complete reading or writing within one second and turn back to 0. After RWAIT is set to 1, it takes up to one f_{RTC} clock cycle before reading/writing the count value is enabled (RWST = 1). When the internal counter (16-bit) overflowed while RWAIT = 1, it keeps the event of overflow until RWAIT = 0, then counts up.Notes 1, 2 However, when it wrote a value to second count register, it will not keep the overflow event.	

Correct:

Figure 8 - 8 Format of Real-time clock control register 1 (RTCC1) (3/3)

Address: FFF9EH After reset: 00H R/W

Symbol	<7>	<6>	<5>	<4>	<3>	2	<1>	<0>
RTCC1	WALE	WALIE	RITE	WAFG	RIFG	0	RWST	RWAIT

RWST	Wait status flag of real-time clock 2
0	Counter is operating.
1	Mode to read or write counter value.
This status flag indicates whether the setting of the RWAIT bit is valid. Before reading or writing the counter value, confirm that the value of this flag is 1. Even if the RWAIT bit is set to 0, the RWST bit is not set to 0 while writing to the counter. After writing is completed, the RWST bit is set to 0.	

RWAIT	Wait control of real-time clock 2
0	Sets counter operation.
1	Stops SEC to YEAR counters. Mode to read or write counter value.
This bit controls the operation of the counter. Be sure to write 1 to it to read or write the counter value. As the counter (16-bit) is continuing to run, complete reading or writing within one second and turn back to 0. When reading or writing to the counter is required while generation of the alarm interrupt is enabled, first set the CT2 to CT0 bits to 010B (generating the constant-period interrupt once per 1 second). Then, complete the processing from setting the RWAIT bit to 1 to setting it to 0 before generation of the next constant-period interrupt. After RWAIT is set to 1, it takes up to one f_{RTC} clock cycle before reading/writing the count value is enabled (RWST = 1). When the internal counter (16-bit) overflowed while RWAIT = 1, it keeps the event of overflow until RWAIT = 0, then counts up.Notes 1, 2 However, when it wrote a value to second count register, it will not keep the overflow event.	

2. Figure 8 - 22 Procedure for Reading Real-time Clock 2 (Page 312)

Incorrect:

Note 1. When the counter is stopped (RTCE = 0), RWST is not set to 1.

Note 2. Be sure to confirm that RWST = 0 before setting STOP mode.

Caution Complete the series of operations of setting the RWAIT bit to 1 to clearing the RWAIT bit to 0 within 1 second.

Remark SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR may be read in any sequence. All the registers do not have to be set and only some registers may be read.

Correct:

Note 1. When the counter is stopped (RTCE = 0), RWST is not set to 1.

Note 2. Be sure to confirm that RWST = 0 before setting STOP mode.

Caution Complete the series of operations of setting the RWAIT bit to 1 to clearing the RWAIT bit to 0 within 1 second. When reading to the counter is required while generation of the alarm interrupt is enabled, first set the CT2 to CT0 bits to 010B (generating the constant-period interrupt once per 1 second). Then, complete the processing from setting the RWAIT bit to 1 to setting it to 0 before generation of the next constant-period interrupt.

Remark SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR may be read in any sequence. All the registers do not have to be set and only some registers may be read.

3. Figure 8 - 23 Procedure for Writing Real-time Clock 2 (Page 313)

Incorrect:

Note 1. When the counter is stopped (RTCE = 0), RWST is not set to 1.

Note 2. Be sure to confirm that RWST = 0 before setting STOP mode.

Caution 1. Complete the series of operations of setting the RWAIT bit to 1 to clearing the RWAIT bit to 0 within 1 second.

Caution 2. When changing the values of the SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR register while the counter operates (RTCE = 1), rewrite the values of the MIN register after disabling interrupt servicing INTRTC by using the interrupt mask flag register. Furthermore, clear the WAFG, RIFG and RTCIF flags after rewriting the MIN register.

Remark SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR may be read in any sequence. All the registers do not have to be set and only some registers may be written.

Correct:

Note 1. When the counter is stopped (RTCE = 0), RWST is not set to 1.

Note 2. Be sure to confirm that RWST = 0 before setting STOP mode.

Caution 1. Complete the series of operations of setting the RWAIT bit to 1 to clearing the RWAIT bit to 0 within 1 second. When writing to the counter is required while generation of the alarm interrupt is enabled, first set the CT2 to CT0 bits to 010B (generating the constant-period interrupt once per 1 second). Then, complete the processing from setting the RWAIT bit to 1 to setting it to 0 before generation of the next constant-period interrupt.

Caution 2. When changing the values of the SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR register while the counter operates (RTCE = 1), rewrite the values of the MIN register after disabling interrupt servicing INTRTC by using the interrupt mask flag register. Furthermore, clear the WAFG, RIFG and RTCIF flags after rewriting the MIN register.

Remark SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR may be read in any sequence. All the registers do not have to be set and only some registers may be written.

4. 34.3.2 Supply current characteristics (Page 866 to Page 870)

Incorrect:

34.3.2 Supply current characteristics

(T_A = -40 to +85°C, 1.6 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)

(T_A = +85 to +105°C, 2.4 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V) **(1/4)**

Parameter	Symbol	Conditions						MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD1}	Operating mode	HS (high-speed main) mode	f_{IH} = 24 MHz Note 3, T_A = -40 to +85°C	Basic operation	V_{DD} = 3.0 V			1.4		mA
			LP (low-power main) mode (MCSEL = 1)	f_{MX} = 1 MHz Note 2, T_A = -40 to +85°C	Normal operation	V_{DD} = 3.0 V	Square wave input		100	190	µA
							Resonator connection		136	250	
				f_{MX} = 1 MHz Note 2, T_A = -40 to +85°C	Normal operation	V_{DD} = 2.0 V	Square wave input		100	190	
							Resonator connection		136	250	

(T_A = -40 to +85°C, 1.6 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)

(T_A = +85 to +105°C, 2.4 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V) **(2/4)**

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD1}	Operating mode	Subsystem clock operation	f_{SX} = 32.768 kHz, T_A = -40°C Note 4	Normal operation	Square wave input		3.2	6.1	µA
						Resonator connection		3.3	6.1	
				f_{IL} = 15 kHz, T_A = +85°C Note 6	Normal operation			2.3	8.7	
				f_{IL} = 15 kHz, T_A = +105°C Note 6	Normal operation			3.0	20.9	

Note 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. **The MAX values include the peripheral operating current. However, these values do not include the current flowing into the A/D converter, operational amplifier, comparator, LVD circuit, I/O ports, and on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.**

Note 2. When the high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Note 3. When the high-speed system clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Note 4. When the high-speed system clock, high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped. When ultra-low-power consumption oscillation is set (AMPHS1, AMPHS0) = (1, 0). **The values do not include the current flowing into the real-time clock 2, 12-bit interval timer, and watchdog timer.**

Correct:

34.3.2 Supply current characteristics

(T_A = -40 to +85°C, 1.6 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)

(T_A = +85 to +105°C, 2.4 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V) **(1/4)**

Parameter	Symbol	Conditions						MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD1}	Operating mode	HS (high-speed main) mode	f_{IH} = 24 MHz Note 3, T_A = -40 to +85°C	Basic operation	V_{DD} = 3.0 V			1.4		mA
			LP (low-power main) mode (MCSEL = 1)	f_{MX} = 1 MHz Note 2, T_A = -40 to +85°C	Normal operation	V_{DD} = 3.0 V	Square wave input		100	190	µA
							Resonator connection		136	250	
				f_{MX} = 1 MHz Note 2, T_A = -40 to +85°C	Normal operation	V_{DD} = 2.0 V	Square wave input		100	190	
							Resonator connection		136	250	

(T_A = -40 to +85°C, 1.6 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)

(T_A = +85 to +105°C, 2.4 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V) **(2/4)**

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD1}	Operating mode	Subsystem clock operation	f_{SX} = 32.768 kHz, T_A = -40°C Note 4	Normal operation	Square wave input		3.2	6.1	µA
						Resonator connection		3.3	6.1	
				f_{IL} = 15 kHz, T_A = +85°C Note 6	Normal operation			2.3	8.7	
				f_{IL} = 15 kHz, T_A = +105°C Note 6	Normal operation			3.0	20.9	

Note 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The following points apply in the HS (high-speed main), LS (low-speed main), LV (low-voltage main), and LP (low-power main) modes.

- The currents in the “TYP.” column do not include the operating currents of the peripheral modules.
- The currents in the “MAX.” column include the operating currents of the peripheral modules, except for those flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors, and those flowing while the data flash memory is being rewritten.

In the subsystem clock operation, the currents in both the “TYP.” and “MAX.” columns do not include the operating currents of the peripheral modules. However, in HALT mode, including the current flowing into the real-time clock 2.

Note 2. When the high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Note 3. When the high-speed system clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Note 4. When the high-speed system clock, high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped. When ultra-low-power consumption oscillation is set (AMPHS1, AMPHS0) = (1, 0).

Note 5. When the high-speed system clock, high-speed on-chip oscillator clock, sub clock, and low-speed on-chip oscillator clock are stopped. **The MAX values include the current of peripheral operation except BGO operation, and the STOP leakage current. However, the real-time clock 2, watchdog timer, LVD circuit, and A/D converter are stoppe3d.**

Note 6. When the high-speed system clock, high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, and sub clock are stopped.

Note 7. When the high-speed system clock, high-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Remark 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

Remark 2. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

Remark 3. f_{IM}: Middle-speed on-chip oscillator clock frequency (4 MHz max.)

Remark 4. f_{IL}: Low-speed on-chip oscillator clock frequency

Remark 5. f_{SX}: Sub clock frequency (XT1 clock oscillation frequency)

Remark 6. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency or low-speed on-chip oscillator clock frequency)

Remark 7. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

Note 5. When the high-speed system clock, high-speed on-chip oscillator clock, sub clock, and low-speed on-chip oscillator clock are stopped.

Note 6. When the high-speed system clock, high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, and sub clock are stopped.

Note 7. When the high-speed system clock, high-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Remark 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

Remark 2. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

Remark 3. f_{IM}: Middle-speed on-chip oscillator clock frequency (4 MHz max.)

Remark 4. f_{IL}: Low-speed on-chip oscillator clock frequency

Remark 5. f_{SX}: Sub clock frequency (XT1 clock oscillation frequency)

Remark 6. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency or low-speed on-chip oscillator clock frequency)

Remark 7. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

(T_A = -40 to +85°C, 1.6 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)

(T_A = +85 to +105°C, 2.4 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V) **(3/4)**

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD2} Note 2	HALT mode	HS (high-speed main) mode	f_{IH} = 24 MHz Note 4, T_A = -40 to +85°C	V_{DD} = 3.0 V		0.37	1.83	mA
				f_{IL} = 15 kHz, T_A = +85°C Note 6			0.80	3.30	
				f_{IL} = 15 kHz, T_A = +105°C Note 6			2.00	17.30	

Note 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. **The MAX values include the peripheral operating current. However, these values do not include the current flowing into the A/D converter, operational amplifier, comparator, LVD circuit, I/O ports, and on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.**

Note 2. When the HALT instruction is executed in the flash memory.

Note 3. When the high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Note 4. When the high-speed system clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Note 5. When the high-speed system clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and highspeed on-chip oscillator clock are stopped. When RTCLPC = 1 and ultra-low-power consumption oscillation is set (AMPHS1, AMPHS0) = (1, 0). **The values include the current flowing into the real-time clock 2. However, the values do not include the current flowing into the 12-bit interval timer and watchdog timer.**

Note 6. When the high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, high-speed system clock, and sub clock are stopped.

Note 7. When the high-speed system clock, high-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Remark 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

Remark 2. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

Remark 3. f_{IM}: Middle-speed on-chip oscillator clock frequency (4 MHz max.)

Remark 4. f_{IL}: Low-speed on-chip oscillator clock frequency

Remark 5. f_{SX}: Sub clock frequency (XT1 clock oscillation frequency)

Remark 6. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency or low-speed on-chip oscillator clock frequency)

Remark 7. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

(T_A = -40 to +85°C, 1.6 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)

(T_A = +85 to +105°C, 2.4 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V) **(3/4)**

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD2} Note 2	HALT mode	HS (high-speed main) mode	f_{IH} = 24 MHz Note 4, T_A = -40 to +85°C	V_{DD} = 3.0 V		0.37	1.83	mA
				f_{IL} = 15 kHz, T_A = +85°C Note 6			0.80	3.30	
				f_{IL} = 15 kHz, T_A = +105°C Note 6			2.00	17.30	

Note 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The following points apply in the HS (high-speed main), LS (low-speed main), LV (low-voltage main), and LP (low-power main) modes.
- The currents in the “TYP.” column do not include the operating currents of the peripheral modules.
- The currents in the “MAX.” column include the operating currents of the peripheral modules, except for those flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors, and those flowing while the data flash memory is being rewritten.

In the subsystem clock operation, the currents in both the “TYP.” and “MAX.” columns do not include the operating currents of the peripheral modules. However, in HALT mode, including the current flowing into the real-time clock 2.

Note 2. When the HALT instruction is executed in the flash memory.

Note 3. When the high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Note 4. When the high-speed system clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Note 5. When the high-speed system clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and highspeed on-chip oscillator clock are stopped. When RTCLPC = 1 and ultra-low-power consumption oscillation is set (AMPHS1, AMPHS0) = (1, 0).

Note 6. When the high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, high-speed system clock, and sub clock are stopped.

Note 7. When the high-speed system clock, high-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Remark 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

Remark 2. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

Remark 3. f_{IM}: Middle-speed on-chip oscillator clock frequency (4 MHz max.)

Remark 4. f_{IL}: Low-speed on-chip oscillator clock frequency

Remark 5. f_{SX}: Sub clock frequency (XT1 clock oscillation frequency)

Remark 6. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency or low-speed on-chip oscillator clock frequency)

Remark 7. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

(T_A = -40 to +85°C, 1.6 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)

(T_A = +85 to +105°C, 2.4 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V) **(4/4)**

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD3} Note 2	STOP mode Note 3	T_A = -40°C		0.16	0.51	μA
			T_A = +25°C		0.22	0.51	
			T_A = +50°C		0.27	1.10	
			T_A = +70°C		0.37	1.90	
			T_A = +85°C		0.60	3.30	
			T_A = +105°C		1.50	17.00	

Note 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. **The MAX values include the peripheral operating current. However, these values do not include the current flowing into the A/D converter, operational amplifier, comparator, LVD circuit, I/O ports, and on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.**

Note 2. **The values do not include the current flowing into the real-time clock 2, 12-bit interval timer, and watchdog timer.**

Note 3. For the setting of the current values when operating the subsystem clock in STOP mode, see the current values when operating the subsystem clock in HALT mode.

(T_A = -40 to +85°C, 1.6 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)

(T_A = +85 to +105°C, 2.4 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V) **(4/4)**

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD3}	STOP mode Note 2	T_A = -40°C		0.16	0.51	μA
			T_A = +25°C		0.22	0.51	
			T_A = +50°C		0.27	1.10	
			T_A = +70°C		0.37	1.90	
			T_A = +85°C		0.60	3.30	
			T_A = +105°C		1.50	17.00	

Note 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}.
In the STOP mode, the currents in both the “TYP.” and “MAX.” columns do not include the operating currents of the peripheral modules.

Note 2. For the setting of the current values when operating the subsystem clock in STOP mode, see the current values when operating the subsystem clock in HALT mode.